

ABSTRACT OF THE DISCLOSURE

A substrate treating apparatus and substrate treating method for performing at least cleaning treatment of substrates. The substrate are cleaned in a treating tank while a cleaning liquid (deionized water) is introduced into the treating tank through a bottom thereof and an excess amount of the cleaning liquid is allowed to overflow the tank. During the treatment, a feeding flow rate of the cleaning liquid is varied with time, to prevent a stagnation of flows in the tank and promote the effect of removing particles. The cleaning liquid in the tank is not drawn off quickly, to avoid unnecessary vibration being applied to the substrates.